PCN Number: 201708040		000C			PC	N Date:	Oct 17, 2017			
Title: Qualification of UTAC Thailand as additional Assembly and Test Site for Select I					Select Devices					
Cus	Customer Contact: PCN Manager Dept: Quality Services									
Pro	Proposed 1 st Ship Date: Nov 09, 2017 Estimated Sample Availability: Date Provided at Sample request									
Cha	nge Type:									
	Assembly S					Design				Sump Site
	Assembly F					Data She		Щ		Sump Material
	Assembly M		. 4.1				ber change	H		Sump Process
\mathbb{H}	Mechanical	•		~		Test Prod		H	Wafer F	ab Site ab Materials
	Packing/Sh	пррину/ с	abelling	J		Test Prod	Less	H		ab Process
						PCN Deta	ile		Water i	ab 110cess
Des	cription of	Change			•	CIV Deta	1113			
				cripti	on of c	hange to in	clude Cu wire c	hand	ge for dev	vices under
							y have caused.		,	
							ation of UTAC T			
							"Product Affec	ted"	Section.	Current
asse	embly sites a	and Matei	riai din	reren	ces are	as follows.				
Г	Assembly S	Site As	sembly	v Site	Origin	Assembly	/ Country Code		Assembl	y Site City
	TI Clark			QAB	og	7.000	PHL	Д		y, Pampanga
	UTAC Thail			NSE			THA	Bangkok		
						ı				3
Mat	erial Differ	ences G	roup :	1:						<u>_</u>
						TI Clark	UTAC	Tha	iland	
		Lead fir	nish			NiPdAu	Ma	itte s	Sn	
			int compound					Z013		
		Mold co	mpou	nd		4208625	C	Z035	51	
Mad	orial Diffor		"	3.						
Mat	erial Differ	ences G	roup a	<u>Z:</u>		TI Clark	UTAC	Tha	iland	
		Lond fin	iah							
		Lead fir Wire ty				NiPdAu Au	IMIC	tte ! Cu	511	
		Mount		und		4207123	D ⁻	Z013	28	
		Mold co						CZ0351		
	11010 00111100110 1200025 020011									
Upo	Upon expiration of this PCN, TI will combine lead finish solutions in a single standard part									
							ith both Matte S			
			specif	fy NiP	dAu fir	iish by orde	ring the part w	ith t	he E4 sut	ffix, e.g.
"TP	"TPS51362RVERE4."									
Test coverage, insertions, conditions will remain consistent with current testing and verified with										
test MQ.										
Reason for Change:										
Continuity of Supply										
Anticipated impact on Material Declaration										
	No Impact						ns or Product Co	onte	nt reports	are driven from
	Material De			_			d will be availab			
							luction release			
				0	btained	I from the 1	<u> I Eco-Info web</u>	<u>site</u> .	There is	no impact to the
Ī	1		1	n	atorial	mooting of	irrent regulator		malianca	ma autina ma anta

with this PCN change.

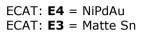
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site			
TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB	ECAT: E4
UTAC Thailand	Assembly Site Origin (22L)	ASO: NSE	ECAT: E3

Sample product shipping label (not actual product label)





MADE IN: Malaysia 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

OPT: 1750 LBL: 5A (L)TO:1750 (1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483\$I2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: TI-Clark = I, UTAC Thailand = J

Group 1 Product Affected:

CSD59930Q4M	CSD97396Q4M	SN1402065RVER	TPS53915RVER
CSD59935Q4M	CSD97396Q4MT	SN1402065RVET	TPS53915RVET
CSD59998Q4M	FX021	TPS53513RVER	TPS548A20RVER
CSD95377Q4M	FX026	TPS53513RVET	TPS548A20RVET
CSD95377Q4MT	FX033	TPS53515RVER	TPS549A20RVER
CSD97374Q4M	FX033Z	TPS53515RVET	TPS549A20RVET
CSD97395Q4M	HPA02240RVER	TPS53913RVER	
CSD97395Q4MT	SN1401043RVER	TPS53913RVET	

Group 2 Product Affected:

CSD59924Q4M	TPS51362RVER	TPS51367RVER	TPS59367RVER
DPA02259RVER	TPS51362RVET	TPS51367RVET	TPS59367RVET
SN1409027RVER	TPS51363RVER	TPS53515ARVER	
SN1607023RVER	TPS51363RVET	TPS53515ARVET	

Qualification Plan Offload of Power Stage Clip QFN Devices from TI Clark to UTL1 (UTAC) Phase 1

(Qual target date: Oct 30, 2017)

Product Attributes

Attributes	Qual Device: CSD97374Q4M	Qual Device: TPS51362RVER
Assembly Site	UTAC1 THAILAND	UTAC1 THAILAND
Package Family	VSON 3.5 X 4.5 (MM)	QFN 4.5 X 3.5 (MM)
Flammability Rating	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	CFAB, MIHO8	CFAB, MIHO 8
Wafer Fab Process	FET, LBC7	FET, LBC7

- Qual Device CSD97374Q4M is qualified at LEVEL2-260C
- Qual Device TPS51362RVER is qualified at LEVEL2-260CX
- Device CSD97374Q4M contains multiple dies.
- Device TPS51362RVER contains multiple dies.

Qualification Results expected Oct 30, 2017

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: CSD97374Q4M	Qual Device: TPS51362RVER
AC	Autoclave, 121C	96 Hours	3/231 - TBD	3/231 - TBD
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231 - TBD	3/231 - TBD
BLR	BLR - Temperature Cycle, -40C / +125C	1000 Cycles	1/32 - TBD	-
ED	Electrical Characterization	Per datasheet parameters	TBD	TBD
CDM	ESD CDM	+/- 500V	3/9 - TBD	3/9 - TBD
HBM	ESD HBM	+/- 2000V	3/9 - TBD	3/9 - TBD
IOL	Intermittent Operating Life	2500, 5000, 10,000 Cycles	3/231 - TBD	-
HTSL	High Temperature Storage Bake, 170C	420 Hours	3/231 - TBD	3/231 - TBD
MSL	Thermal Integrity Sequence (Cu Wire)	Level 2 at 260C	3/36 - TBD	-
MSL	Thermal Integrity Sequence	Level 2 at 260C	-	3/36 - TBD
MQ	Manufacturability (Assembly)	Per Mfg. Site specification	TBD	TBD
PD	Physical Dimensions	Per mechanical drawing	3/15 - TBD	3/15 - TBD
SD	Solderability	Steam age, 8 hours; Pb-Free	3/66 - TBD	3/66 - TBD
SD	Solderability	Steam age, 8 hours; Pb	3/66 - TBD	3/66 - TBD
TC	Temperature Cycle, -55C/125C	700 Cycles	3/231 - TBD	3/231 - TBD

⁻ Preconditioning performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

⁻ The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours.

⁻ The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours.

⁻ The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com